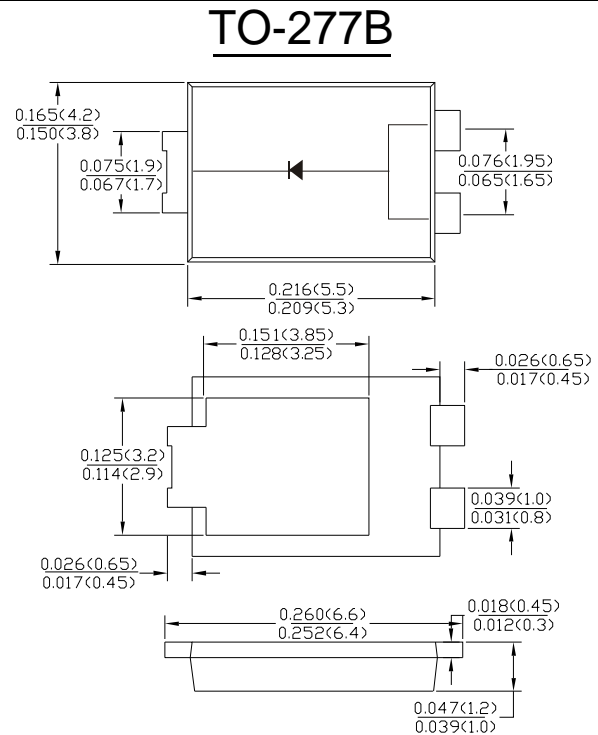


Features

- Schottky Barrier Chip
- High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- High Forward Surge Capability
- Ultra Low Power Loss, High Efficiency
- Excellent High Temperature Stability
- Plastic material-UL flammability 94V-0

Mechanical Data

- Case: TO-277B, molded plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Mounting Position: Any
- Marking: Type Number
- Lead Free: For RoHS/Lead Free Version



dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbol	SB1045L	SB1050L	SB1060L	SB1080L	SB10100L	Unit
Peak Repetitive Reverse Voltage	V_{RRM}						
Working Peak Reverse Voltage	V_{RWM}	45	50	60	80	100	V
DC blocking voltage	V_{DC}						
RMS Rectified Voltage	$V_{R(RMS)}$	32	35	42	56	70	V
Average Rectified Output Current (Note1)	$I_F(AV)$	10					A
Non-Repetitive Peak Forward Surge 8.3ms							
Single Half Sine-Wave Superimposed on rated load (JEDEC Method) (Note2)	I_{FSM}	150					A
I^2t Rating for Fusing ($t < 8.3ms$)	I^2t	93.375					A^2s
Forward Voltage Drop $T_A = 25^\circ\text{C}$ @ $I_F = 10A$	V_{FM}	0.50	0.55	0.75			V
Peak Reverse Current $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage $T_A = 100^\circ\text{C}$	I_R	0.3					mA
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$ $R_{\theta JL}$	80					$^\circ\text{C/W}$
Operating junction temperature range	T_J	-55 to +150					$^\circ\text{C}$
storage temperature range	T_{STG}	-55 to +150					$^\circ\text{C}$

Note: 1. Valid Provided that are kept at ambient temperature at a distance of 9.5mm from the case.

2. Fr-4pcb. 2oz. Copper, minimum recommend pad layout .18.8mm×14.4. Anode pad dimensions 5.6mm×14.4mm.

Fig.1 - Forward Current Derating Curve

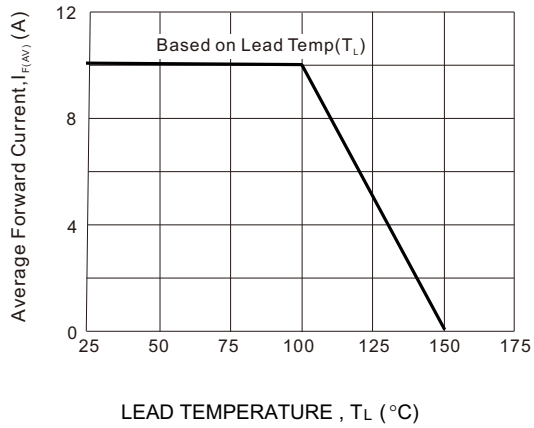


Fig2 : Instantaneous Forward Voltage

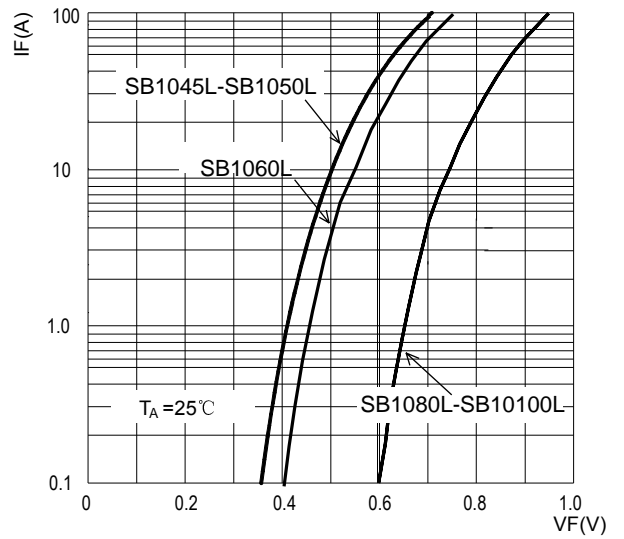


Fig3: Surge Forward Current Capacity

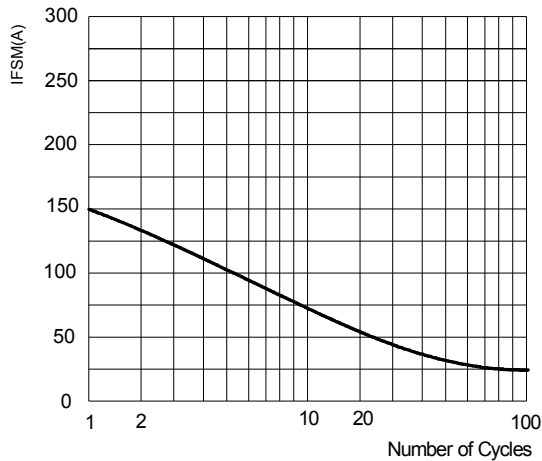


Fig4: Typical Reverse Characteristics

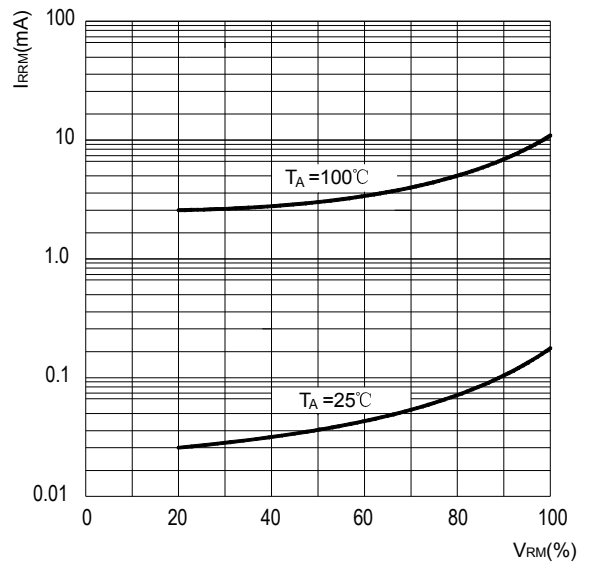


FIG.5 MOUNTING PAD LAYOUT

